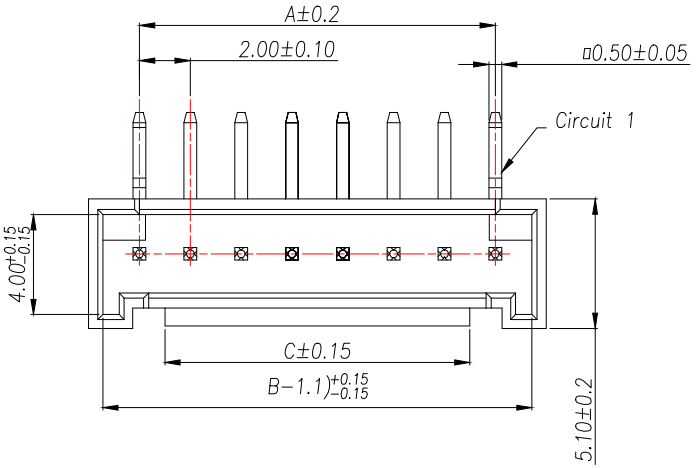
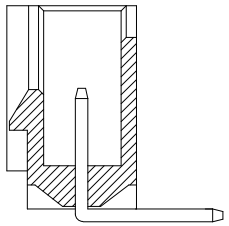
REV.	DESCRIPTION	ECN NO.	NAME	DATE



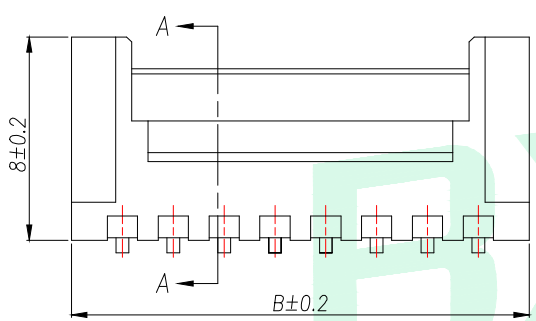

SECTION A−A

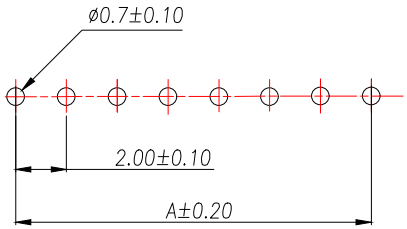
PRELIMINARY
DESIGN IS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE

技术要求:

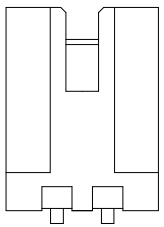
1、塑件材料:PA66
2、接触件:黄铜镀锡
3、接触电阻:≤10mΩ
4、绝缘电阻:≥1000MΩ
5、额定电压:250V AC DC
6、额定电流:2.0A AC DC
7、耐压:能承受1000V AC/Min ute
8、工作温度:−25°~~+85°
9、可焊性试验:浸锡面积≥95%温度220$^{+5}_{0}$°,时间2.5±0.5秒
10、铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B	C
WF-HY2.0-2PWZ	2	2	6	
WF-HY2.0-3PWZ	3	4	8	2
WF-HY2.0-4PWZ	4	6	10	4
WF-HY2.0-5PWZ	5	8	12	6
WF-HY2.0-6PWZ	6	10	14	8
WF-HY2.0-7PWZ	7	12	16	10
WF-HY2.0-8PWZ	8	14	18	12
WF-HY2.0-9PWZ	9	16	20	14
WF-HY2.0-10PWZ	10	18	22	16
WF-HY2.0-11PWZ	11	20	24	18
WF-HY2.0-12PWZ	12	22	26	20
WF-HY2.0-13PWZ	13	24	28	22
WF-HY2.0-14PWZ	14	26	30	24
WF-HY2.0-15PWZ	15	28	32	26





SUGGESTED PCB LAYOUT
(COMPONENT SIDE)


2P外观

序号	名 称	材 料	数 量	附 注
2	Contact	Brass	n*1	电镀(镍):整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色

GENERAL TOLERANCE

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: WAFER 2.0mm H8.0mm 90° DIP

DWG. NO.: WF−HY2.0−XPWZ

DRAWN: MAX

PART NO.: WF−HY2.0−XPWZ

CHECKED: ELLA

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:	APPROVED:
mm	none	1of 1	A4	bxconn	WILL